### The Mu3e Experiment Introduction and Current Status

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### The Mu3e Experiment



- Precision experiment
- Search for  $\mu^+ \rightarrow {\rm e^+e^-e^+}$
- Sensitivity  $< 1 \mbox{ in } 10^{16} \mbox{ decays}$

#### In this talk

- Experimental Concept
- Current Status
- Pixel Sensor Prototypes

### $\mu \rightarrow {\rm eee}$ in the Standard Model

#### Features

- Charged lepton flavor violating
- Via neutrino mixing
- Expected BR( $\mu 
  ightarrow$  eee)  $\ll 10^{-50}$
- Current Limit from Sindrum  ${\rm BR}(\mu \to {\rm eee}) < 1 \cdot 10^{-12}$  @90 % CL

Nucl.Phys. B299(1)

#### Importance

- Observable rate only from New Physics
- Sensitive New Physics Search



### Muon Beamlines at PSI



#### Paul Scherrer Institute

- Villigen, Switzerland
- Currently hosts the
   MEG Experiment

#### Muon Beamlines

- Low energy DC beams
- Current beam lines:  $\approx 1 \cdot 10^8 \, \mu/s \; (\pi E5)$
- Future high intensity beam:  $> 1 \cdot 10^9 \,\mu/{
  m s}$

2x10<sup>9</sup> μ/s 50 ns integration

### Signal and Backgrounds

Signal



- Common vertex
- $\sum \vec{p_i} = 0$
- *p* < 53 MeV

#### Backgrounds Internal Conversion

e+ v1 e+ e

- Common vertex
- $\sum \vec{p_i} \neq 0$
- In-time

#### Combinatorial



- No common vertex
- Out-of-time

Requires  $\sigma_p < 0.5 \, {\rm MeV}$  $\sigma_t < 1 \, {\rm ns}$ 

### Multiple Scattering



 $\theta_{MS} \sim \frac{1}{p} \sqrt{x/X_0}$ 

#### Example

- *p* = 35 MeV
- 200 µm Si
- $\Omega R = 5 \,\mathrm{cm}$
- $\Delta y \approx 1 \,\mathrm{mm}$
- $\rightarrow$  Low material budget

#### Environment

 ${\scriptstyle \bullet}~>10^9~\mu^+$  Decays/s

 μ Beam

Target

- Electrons  $p<53\,\text{MeV}$
- Multiple scattering dominates



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### Full Detector

# $\begin{array}{l} \mbox{Magnetic field} \sim 1\,\mbox{T}\\ \mbox{Continuous readout} \end{array}$



#### Tracker Requirements

- Fast serial readout  $\sim 20\,\text{MHz}$
- Thin  $< 1 \% X_0$
- $80\,\mu m \times 80\,\mu m$  pixel
- +  $1\,\text{cm} \times 2\,\text{cm}$  sensor area

#### Timing

• Resolution  $< 1 \, \text{ns}$ 

### Ultra-Lightweight Mechanics



- 50 µm Silicon sensor
- $25\,\mu m$  Kapton flexprint
- $25\,\mu m$  Kapton support frame
- $ightarrow \sim 1\,$ ‰ Radiation length



### Scintillating Fibres

#### Fibre and SiPM Array

#### Signal Spectrum



- 3-5 layers of fibres
- Readout with SiPM and custom ASIC (StiC)
- Time resolution  $\sim 1 \text{ ns} (^{22}\text{Na-source})$

### Scintillating Tiles

Tile Station

#### Tile Prototype



Time Resolution



- $\sim 0.5\,\text{cm}^3$  per tile
- Readout with SiPM and custom ASIC (StiC)
- Time resolution  $\sim 80 \, \mathrm{ps}$  (testbeam)

### Monolithic Active Pixel Sensors



I. Peric, P. Fischer et al. NIMA 582(2007)876

- HV  $\sim$  70 V (HV-MAPS)
- Fast charge collection by drift
- Thin active zone  $< 20 \, \mu m$
- Cheap, commercial process

### **HV-MAPS** Prototypes





#### **Design Specifications**

- + 80  $\mu m$   $\times$  80  $\mu m$  pixel size
- +  $1\,\text{cm} \times 2\,\text{cm}$  active area

#### MuPix2

- 39  $\mu m \times$  30  $\mu m$  pixel size
- $1.8\,\text{mm}\times1\,\text{mm}$  active area
- Proof of Concept

### MuPix3/4

- $92\,\mu m \times 80\,\mu m$  pixel size
- $2.9 \text{ mm} \times 3.2 \text{ mm}$  active area

### MuPix4 HV-MAPS Prototype



- 92  $\mu m \times$  80  $\mu m$  pixel size
- Global threshold
- Zero-suppressed digital readout
- Timestamps
- Additional readout FPGA





### Single Hit Resolution



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### **Global Efficiency**



### **Pixel Efficiency**



Subpixel Efficiency / 4x4 Pixels



Timing



### Future MuPix Prototypes

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#### MuPix6

- Currently in the lab
- Updated analog part, e.g.2-stage amplifier
- Same geometry

#### MuPix7

- Just submitted
- Fast serial readout
- Full digital logic
- Still small scale prototype

### Cooling with Helium



#### Why Helium?

- Low density, low scattering
- High mobility

#### Temperature Gradient



### Reconstruction

### Reconstruction Efficiency





- > 90 % efficiency for 4-hit tracks
- Dropoff is detector acceptance

#### Momentum Resolution



3-hit track,  $\sigma pprox 1.5 \, {
m MeV}$ 



6-hit track,  $\sigma pprox$  0.2 MeV

- Full GEANT4 simulation
- Custom reconstruction
- No energy loss correction

### Expected Sensitivity



Phase IA: earliest 2016

- $2 \cdot 10^7 \,\mu/s$
- Central pixel layers

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Phase IB: 2017+

- $1\cdot 10^8\,\mu/{
  m s}$
- + Timing
- + 1<sup>st</sup> recurl stations

Phase II: 2019+

- $2\cdot 10^9\,\mu/
  m s$
- Full detector
  - Future Muon Beamline

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### The Mu3e Collaboration



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University Zürich

Heidelberg University

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Mainz University

### Summary and Outlook

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#### Mu3e

- Search for  $\mu^+ \to {\rm e^+e^-e^+}$
- Sensitivity  $< 1 \mbox{ in } 10^{16} \mbox{ decays}$

### Features

- HV-MAPS silicon sensors
- Ultra-thin detector
- Down to 100 ps timing
- Up to  $2\cdot 10^9\,\mu/s$

### In the Future

- First data in 2016+
- Full rate not before 2019



http://www.psi.ch/mu3e

## Backup

### Silicon Pixel Sensors

### Α1

#### Hybrid



- HV  $\sim 700\,V$
- Sensor thickness  $\sim 250\,\mu m$
- Extra material
- Complex and expensive

#### Monolithic Active Pixel Sensor



- HV  $\sim$  70 V (HV-MAPS)
- Thin active zone  $<20\,\mu\text{m}$
- Cheap, commercial process

### Beyond the Standard Model



• e.g. SUSY

• e.g new heavy boson

A2

### Global Efficiency / High Voltage



А3